



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP Pavilion 23xi 23-Inch IPS LED Backlit Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		3
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	PH2
Hex nut screwdriver	M5
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Quick release Base stand
2. Strip the screws from rear cover so that the rear metal cover can be removed , after be turn back;
3. Strip the five screws from panel holder
4. Push up and disassemble the cover from the panel
5. To remove the shielding(contain the other material)
6. Strip the screws
7. Release all materials and put some by ESD

3.2 Optional : Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

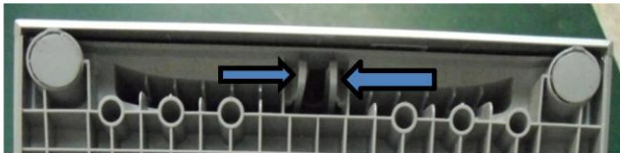
Step 1 Quick release Base stand

(1).Pull out base and stand



- a.Press black button with one hand
- b.Pull out stand & base with another hand

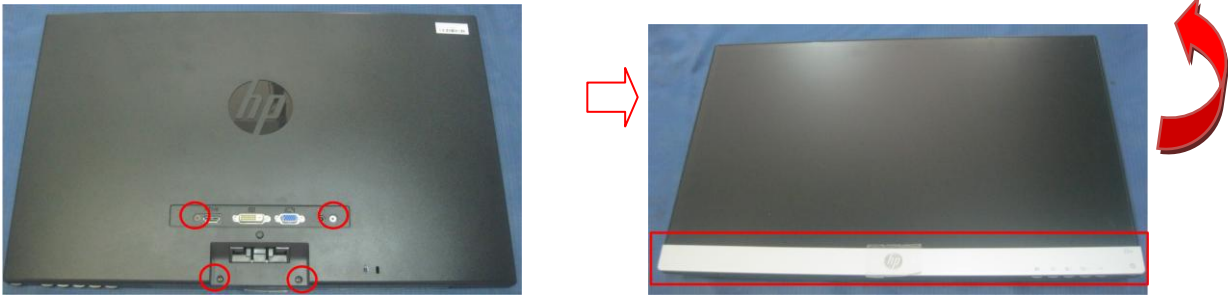
(2).Disassy base and stand



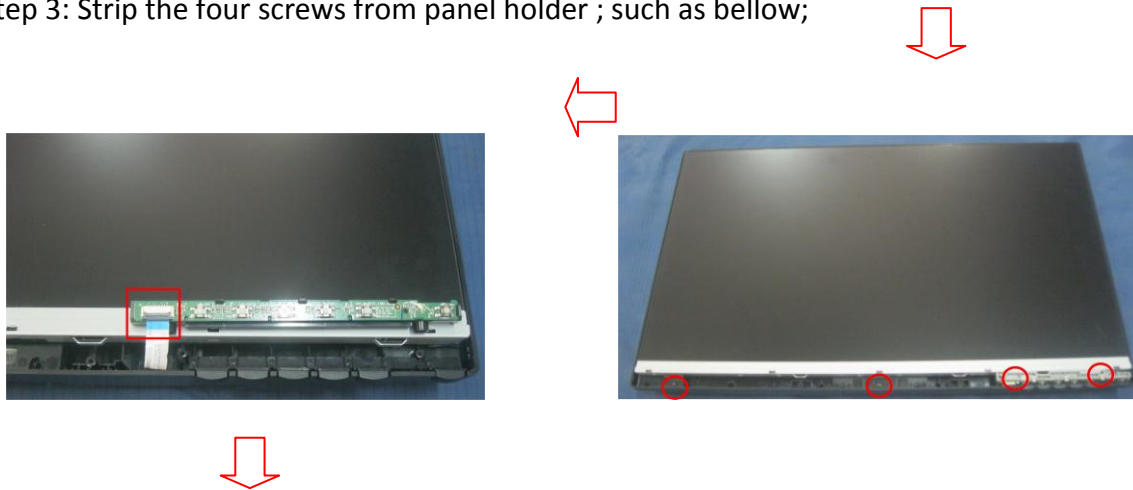
Press this **Plastic Parts,**
then release base



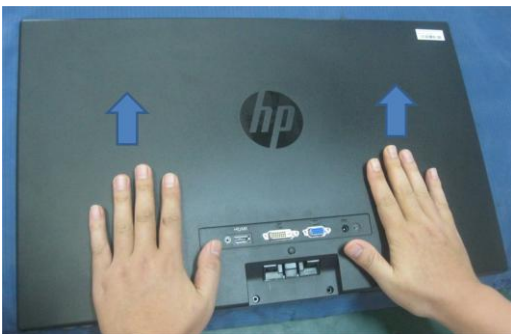
Step 2: Strip the screws from rear cover so that the rear metal cover can be removed , after be turn back;



Step 3: Strip the four screws from panel holder ; such as bellow;



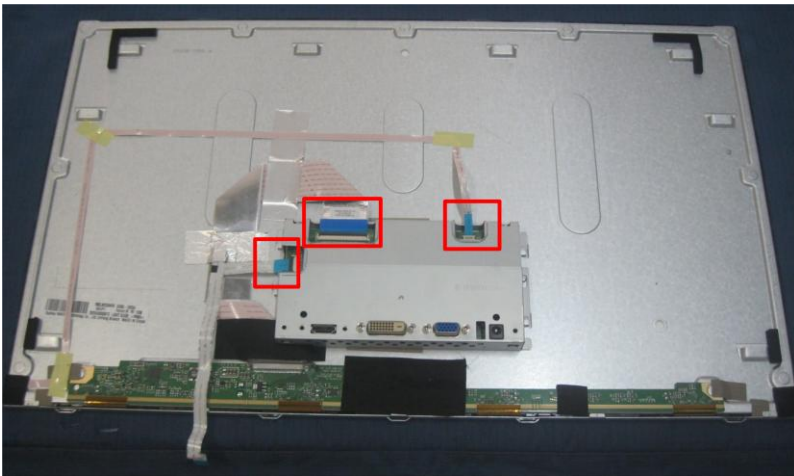
Step 4: Push up and disassemble the cover from the panel;



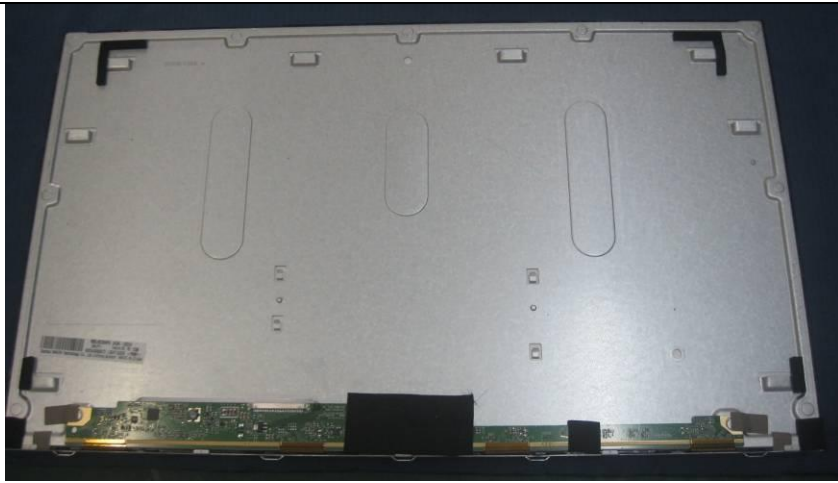
Step 5: To remove the shielding(contain the other material);

(4.1) Remove the acetate tapes covering the LVDS/ LED FFCs;

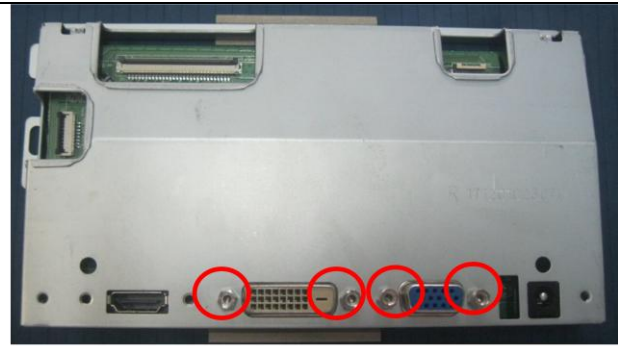
(4.2) Pull out the LVDS/ LED FFCs to separate the base assembly from the unit;



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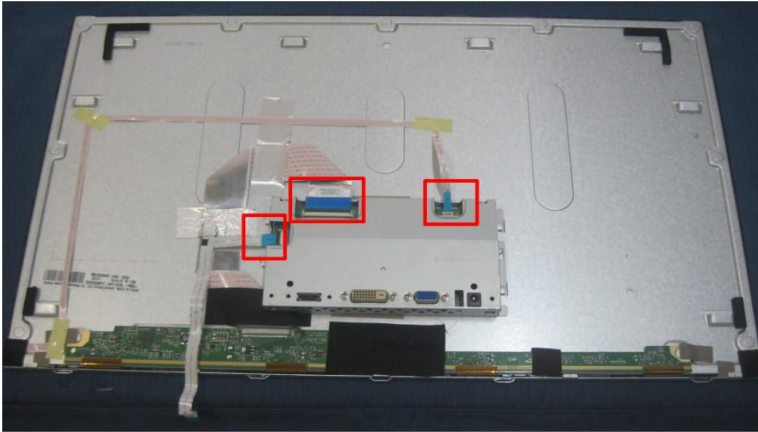


Step 6: Strip the screws *8pcs



Step 7: Release all materials and put some by ESD;

Can follow the picture as bellow;



The overall look when finished



